



25th RD50 Workshop
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Status of Silicon Strip Sensor Measurements at Liverpool

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- Room temperature annealing of RD50 charge multiplication sensors and long-term bias test
- Activation energy (E_g) and current related damage rate (α) determination through IV measurements of irradiated HPK and Micron sensors with fluences up to $2 \times 10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$



Annealing & long-term bias test

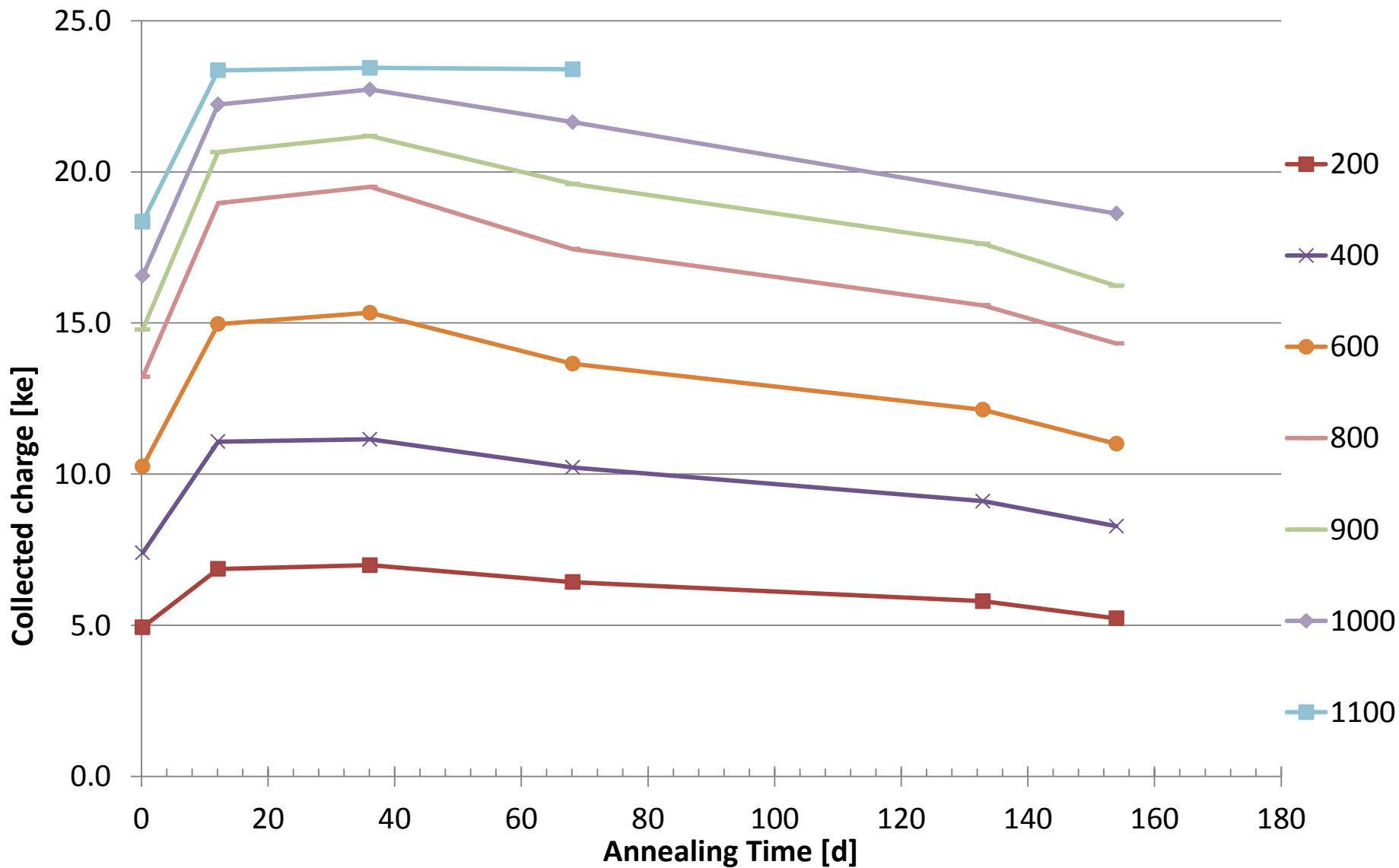


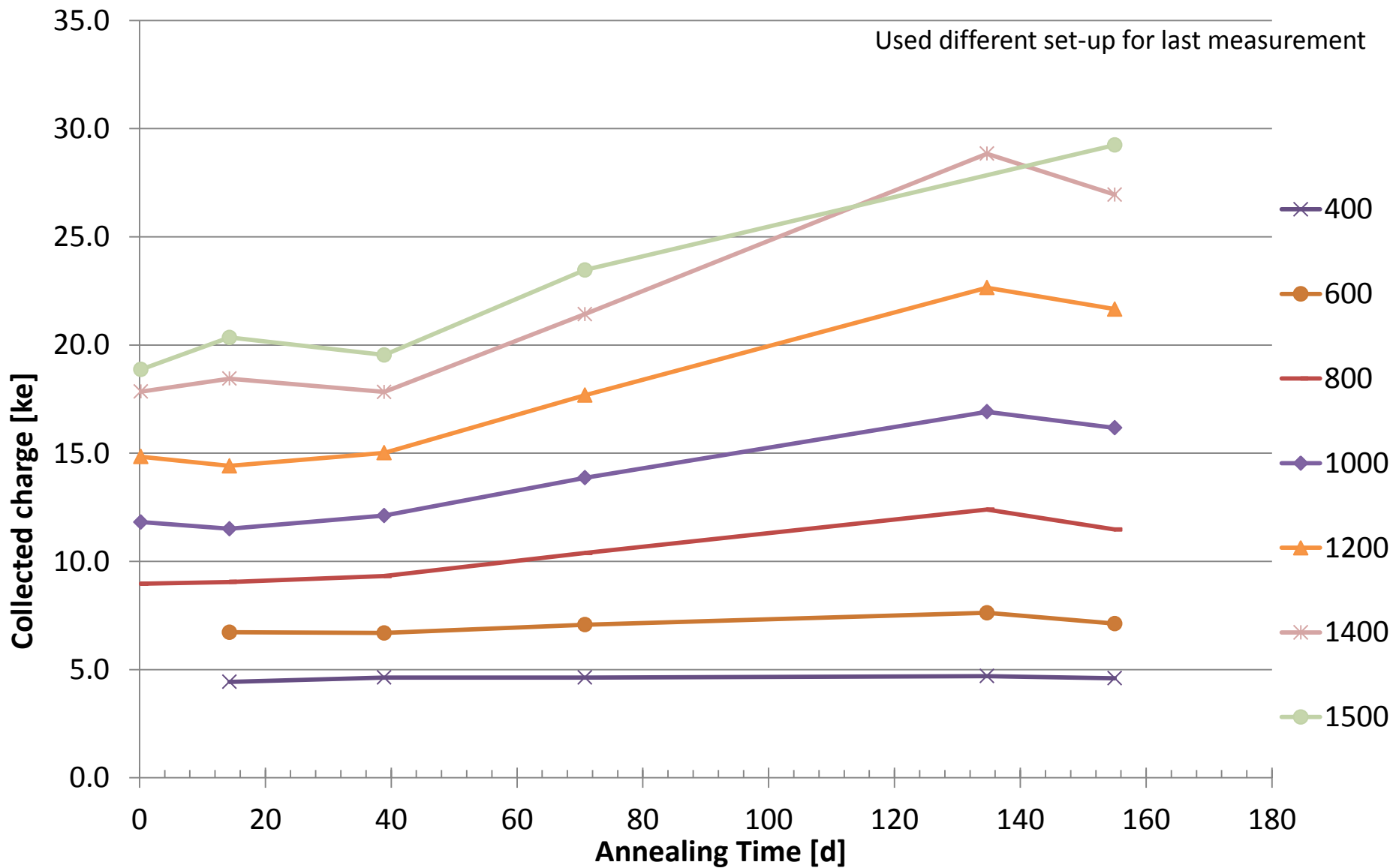
- Dedicated charge multiplication sensors, produced by Micron Semiconductor Ltd (UK)
- 1cm x 1cm, n-in-p FZ strip detectors
- Various strip pitch (P) and width (W)
- Some sensors with biased intermediate strips (I) between readout strips
- Irradiated to two different fluences at Ljubljana
 - $1 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$
 - $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

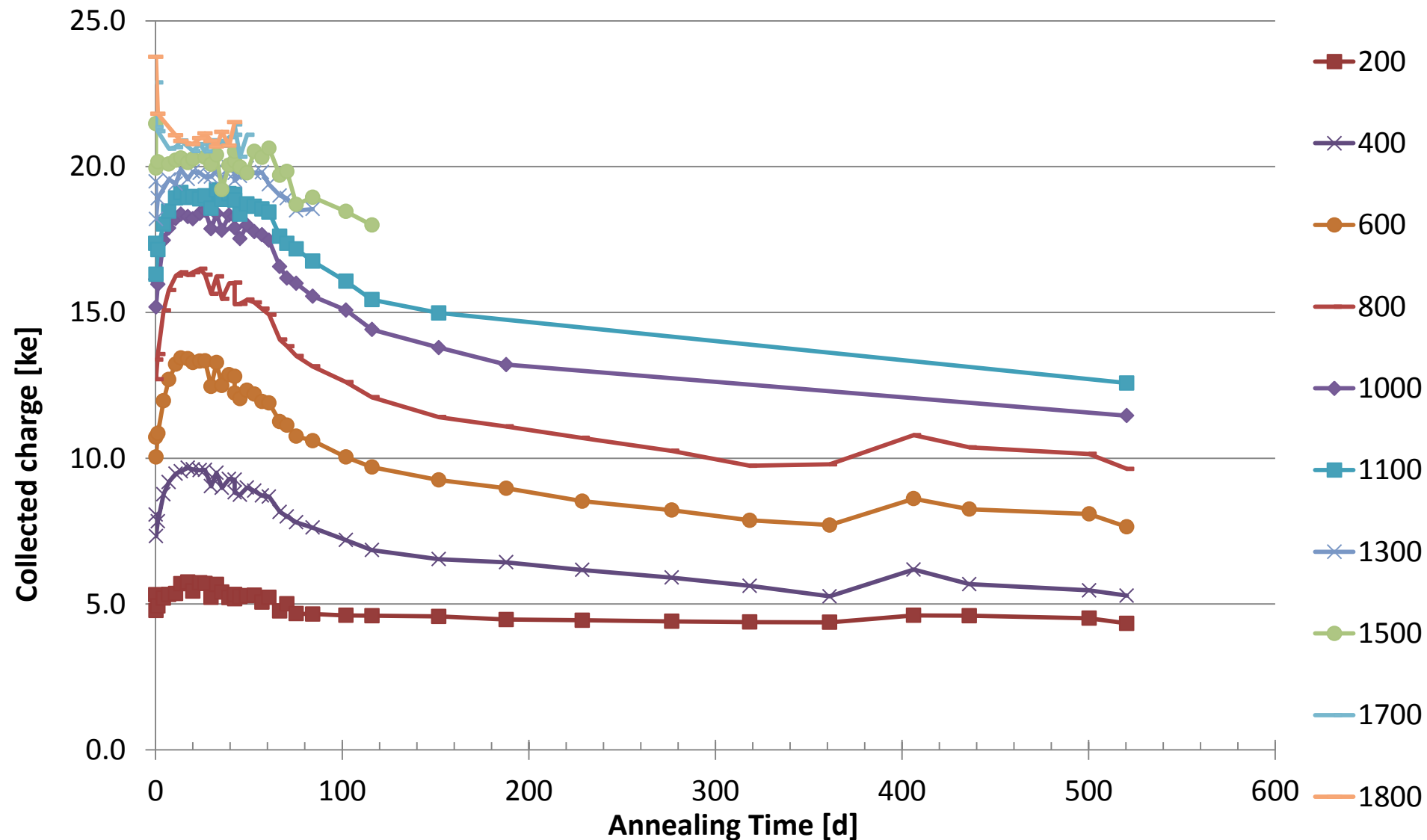


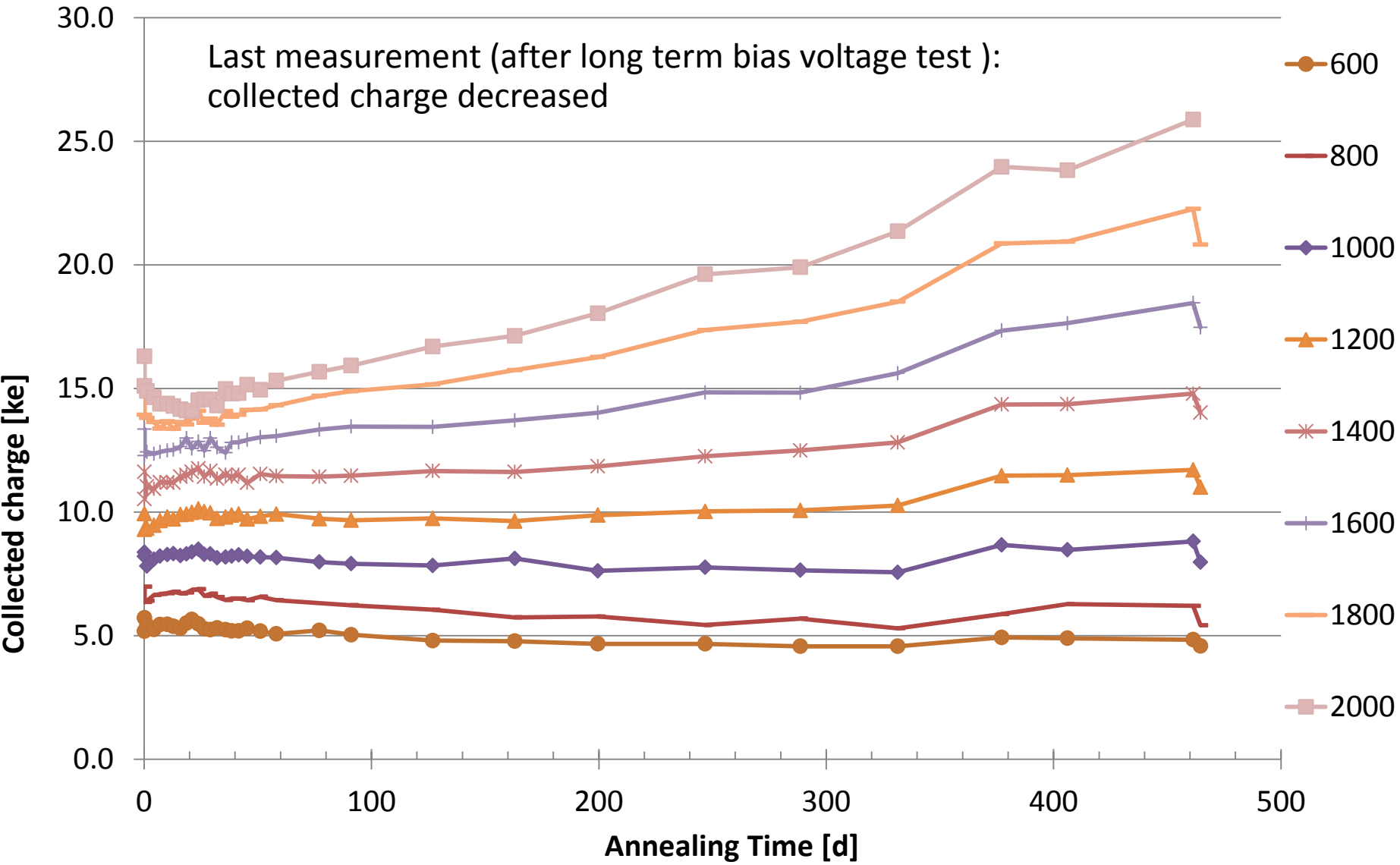
- Room temperature (20°C) annealing in nitrogen cabinet
- Charge collection measurements performed in Beta-setup with the ALiBaVa system











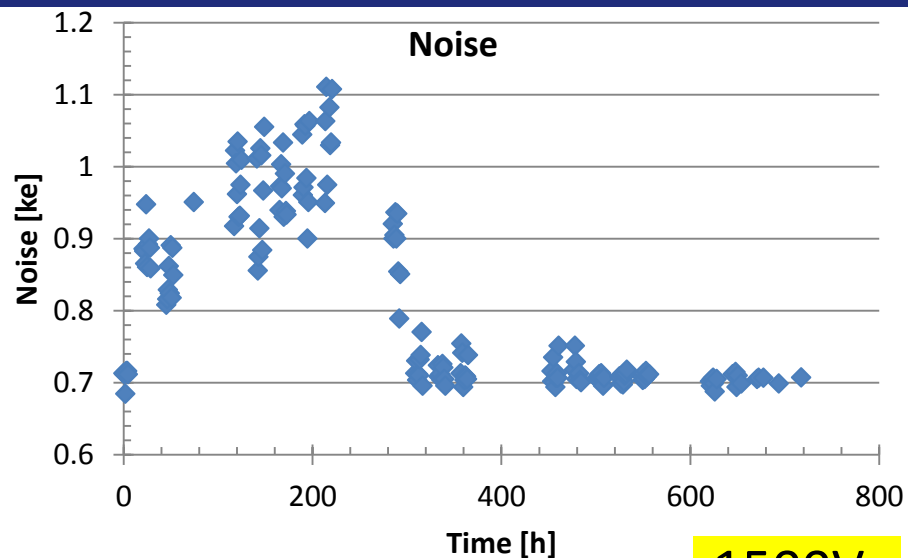
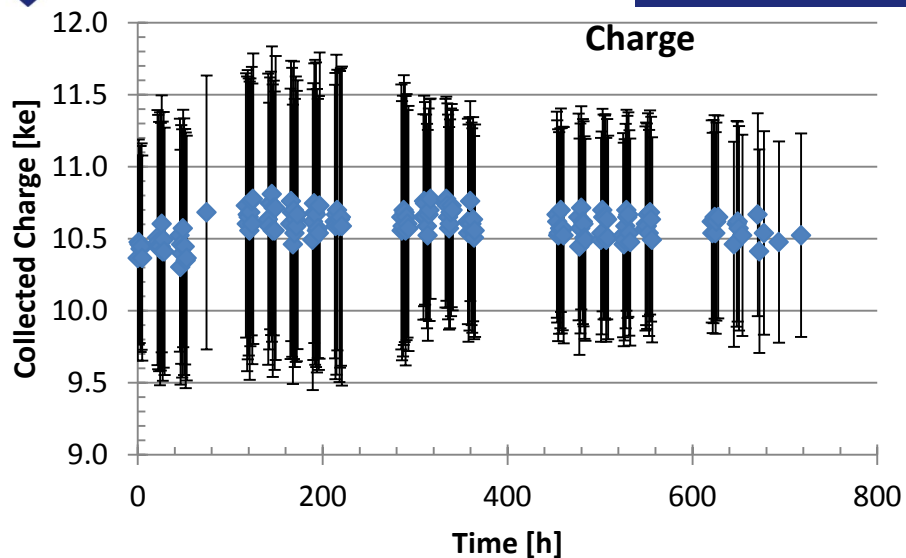


- Irradiated sensors
- Sensor constantly biased
- β source ($\approx 300\text{MBq}$) the whole time above sensor

- Bias voltage above 1000V to see behaviour of charge multiplication

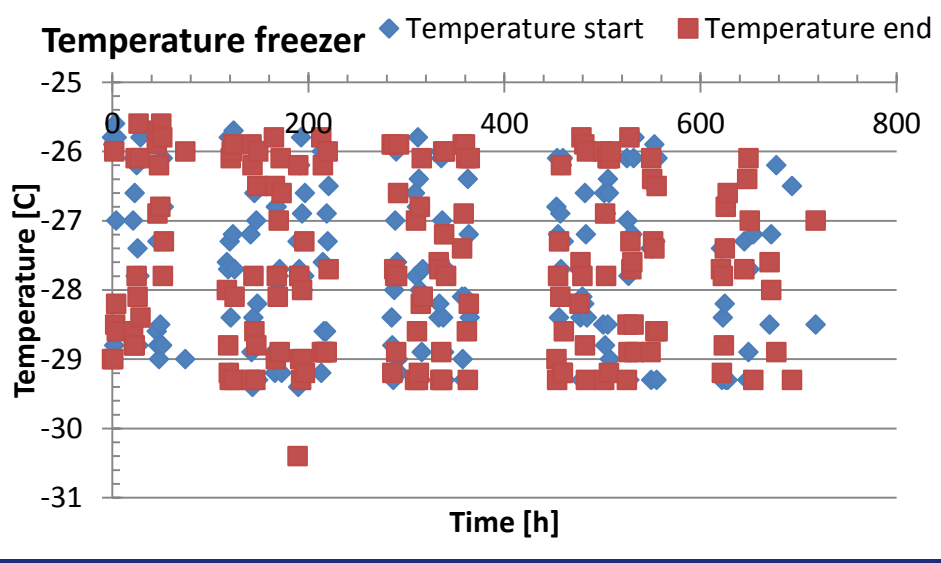
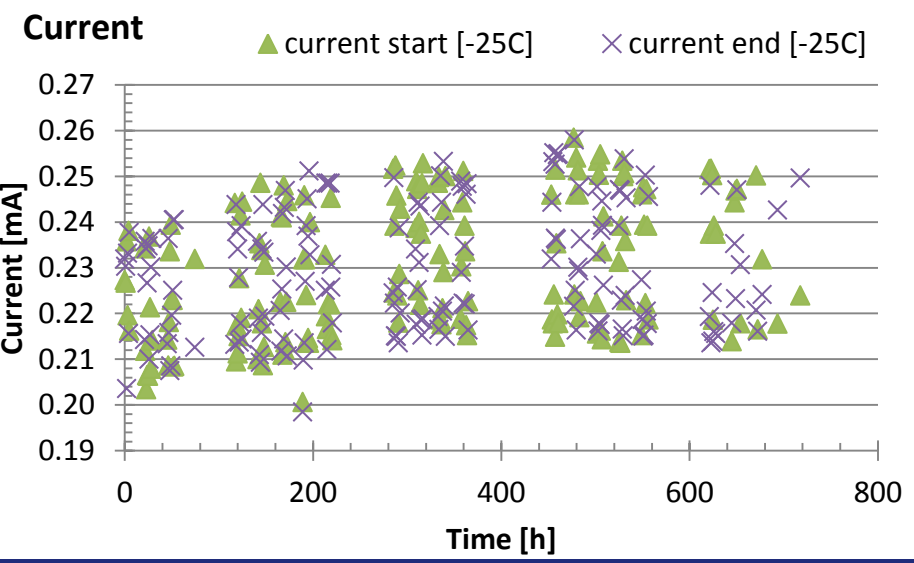
More in talk from Christopher Betancourt Thursday:

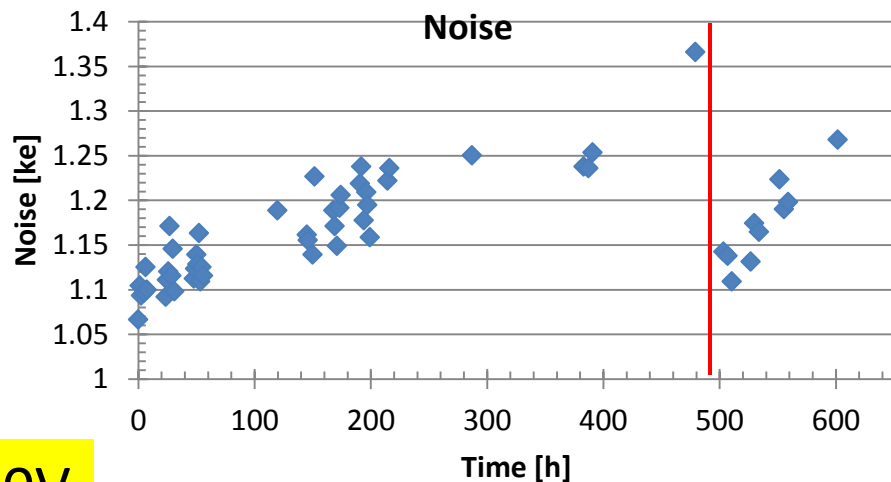
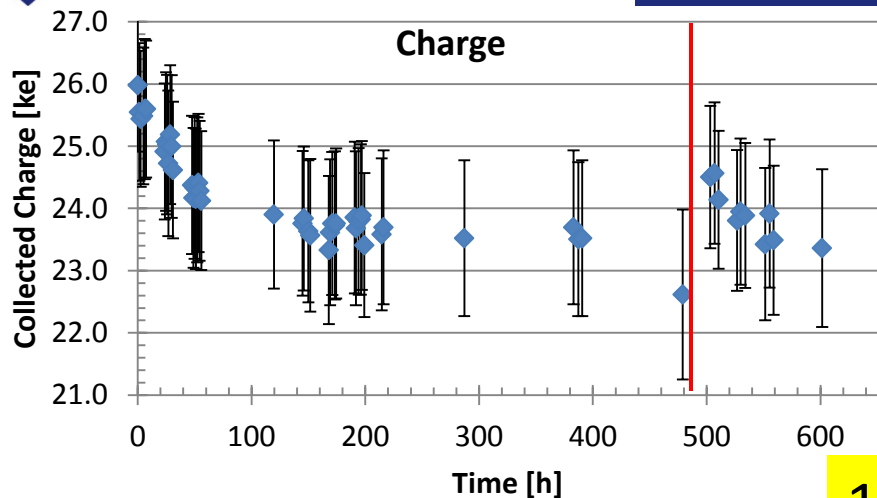
Long-term HV stability of the collected charge in charge multiplication sensors



1500V

No "charge multiplication" in first CCV measurement; not annealing

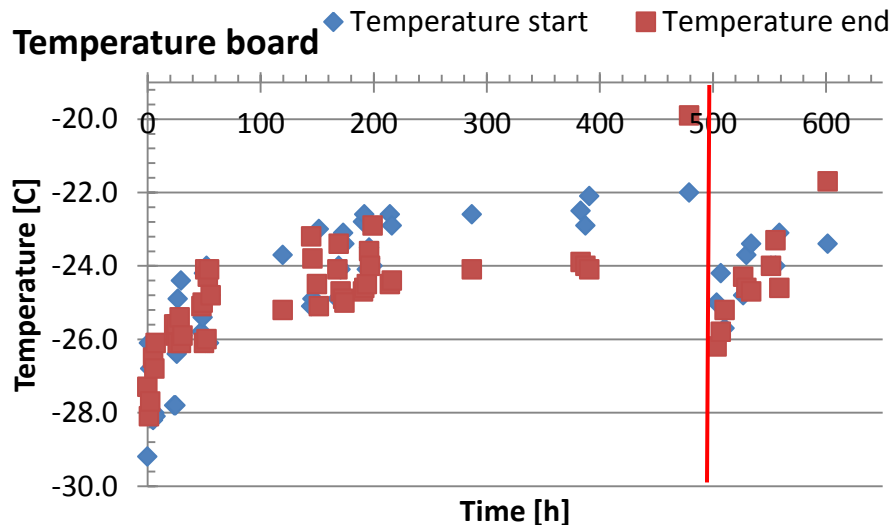
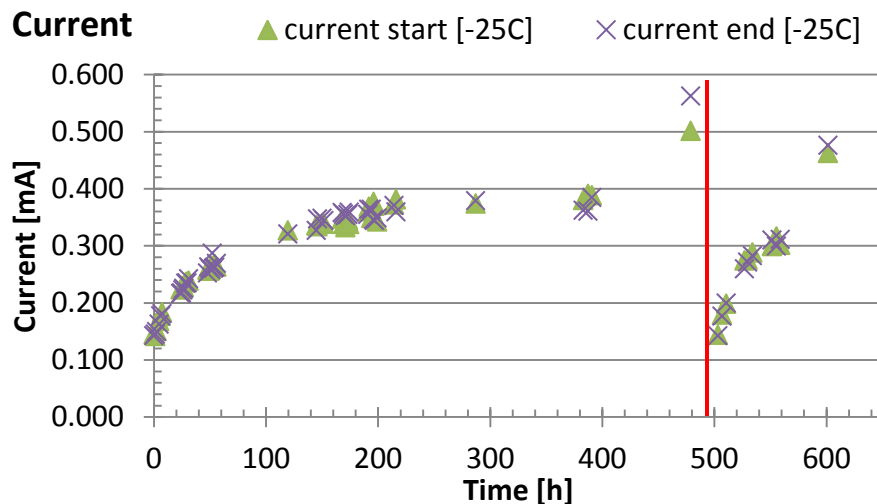




1700V

“charge multiplication” after annealing

During measurement sensor reached compliance (red line) => ramp to 0V, no bias for 1d, then back to 1700V

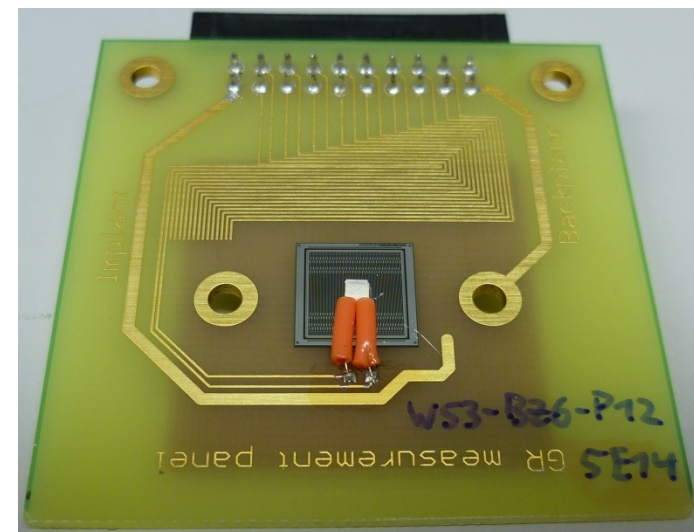




IV Study

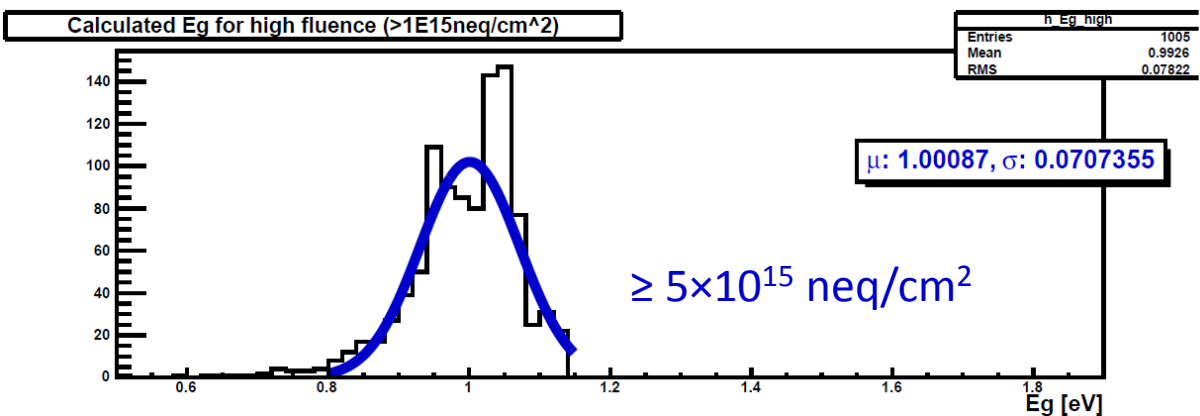
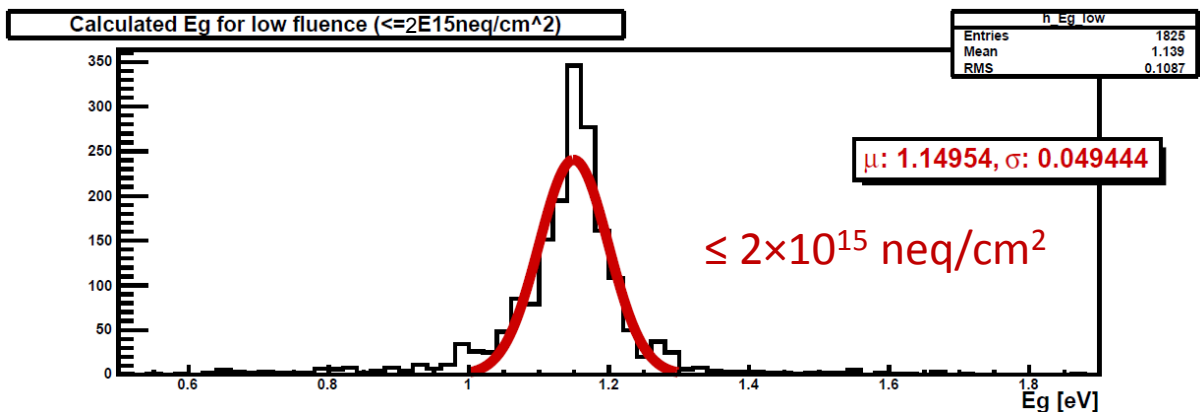
For more details see my talk at RESMDD14:
Leakage Current Measurements of highly irradiated Silicon Strip Sensors

- Silicon sensors ($\sim 1 \times 1$ cm, n-in-p FZ) irradiated to different fluences
 - **ATLAS07 MINI**: 1×10^{12} , 5×10^{12} , 1×10^{13} , 5×10^{13} , 1×10^{14} , **2×10^{14}** , 5×10^{14} , 1×10^{15} , **2×10^{15}** , 5×10^{15} , 1×10^{16} , 1.5×10^{16} , 2×10^{16} [n_{eq}/cm^2]
 - **Micron 2437 (143 μ m)**: **2×10^{14}** , **5×10^{14}** , **1×10^{15}** , **2×10^{15}** , 5×10^{15} , 1×10^{16} , 2×10^{16} [n_{eq}/cm^2]
 - **Micron 2923 (108 μ m)**: **2×10^{14}** , **5×10^{14}** , **2×10^{15}** , 5×10^{15} , 1×10^{16} , 2×10^{16} [n_{eq}/cm^2]
- New measurements (0.3d)**
- PT1000 temperature sensor glued on silicon
 - IV measurements in freezer at different temperatures from -23°C to -15°C (at least 2 per sensor)
 - Different annealing steps (0.3d after glueing, 10d, 30d)





Difference between low fluence ($\leq 2 \times 10^{15} n_{eq}/cm^2$) and high fluence ($\geq 5 \times 10^{15} n_{eq}/cm^2$)



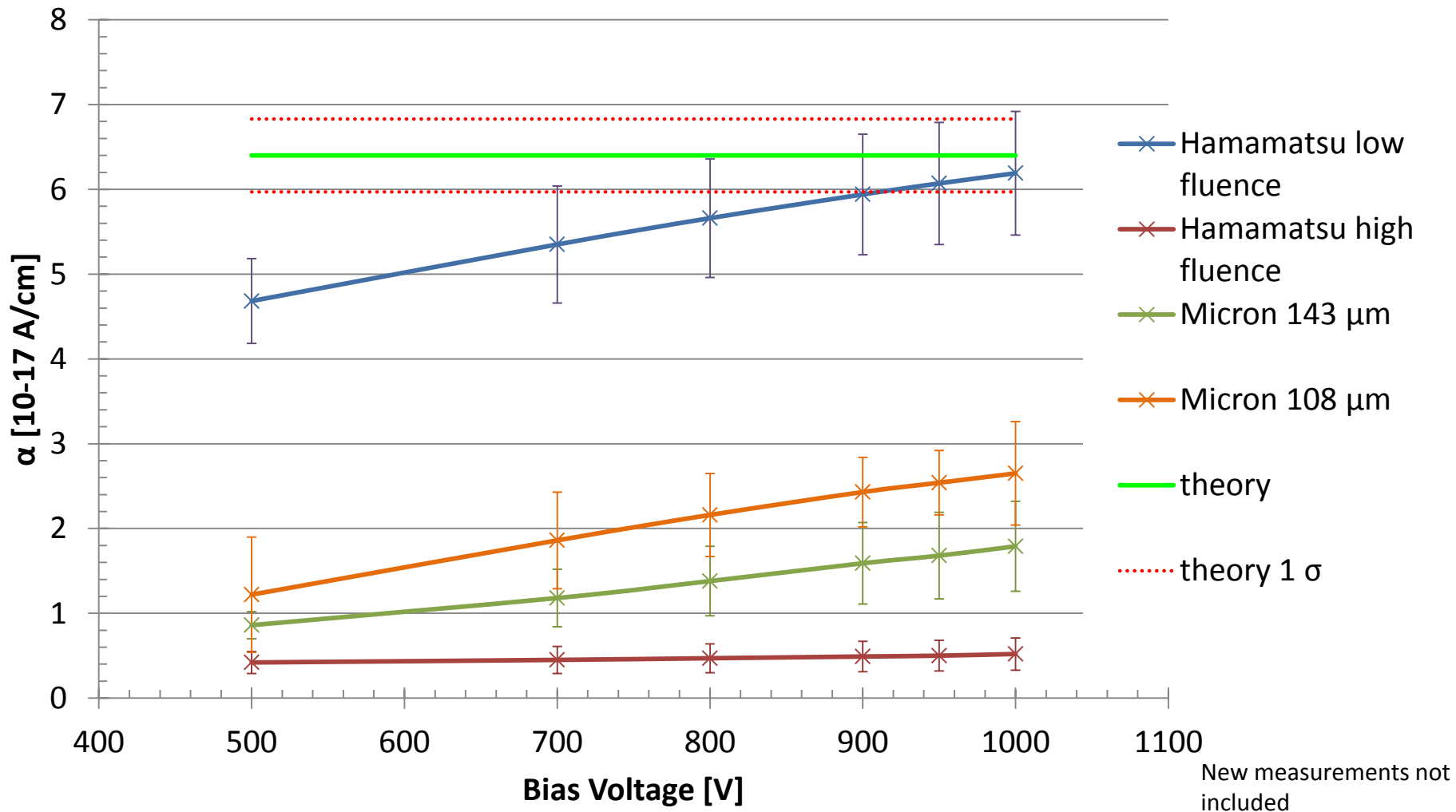
Annealing time	E_g [eV] low fluence	E_g [eV] high fluence
0.3d	1.15 ± 0.05	1.00 ± 0.07
10d	1.17 ± 0.02	1.05 ± 0.06
30d	1.17 ± 0.03	1.07 ± 0.08
theory	1.214 ± 0.014	



Alpha Values (0.3d)

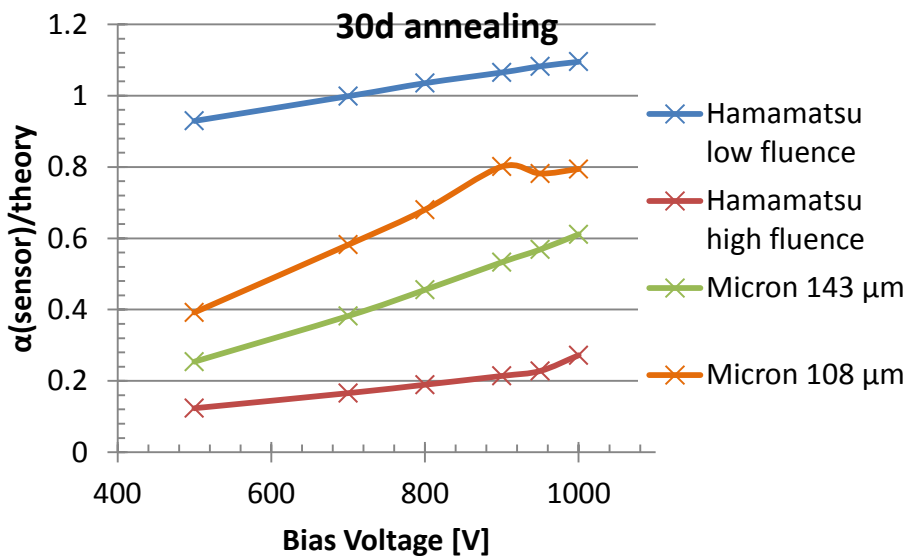
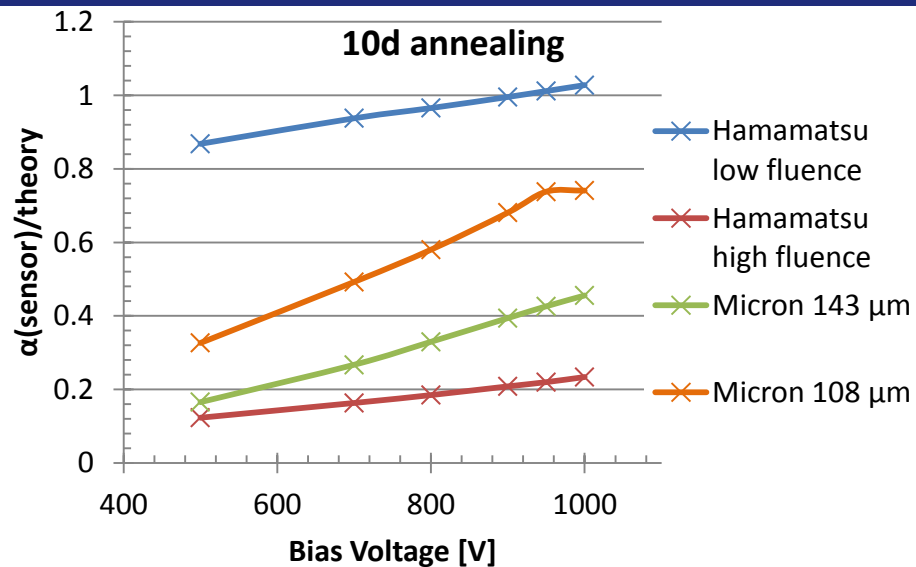
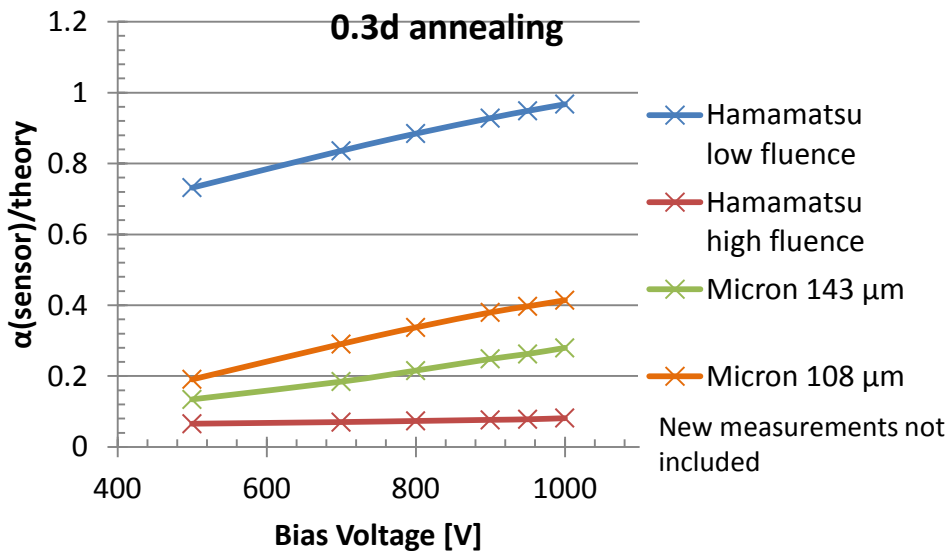
Using the average E_g value for each sensor to calculate the α value:

Straight line fit to ' $\Delta I/V$ vs ϕ ' plot





Relative α after annealing

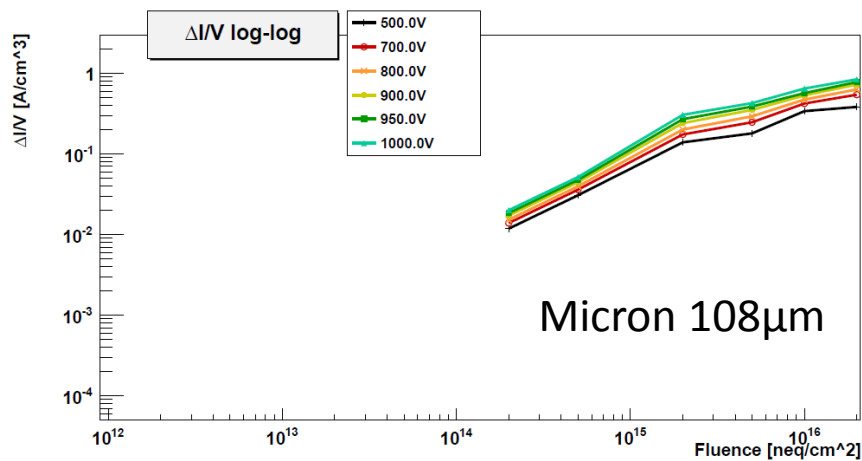
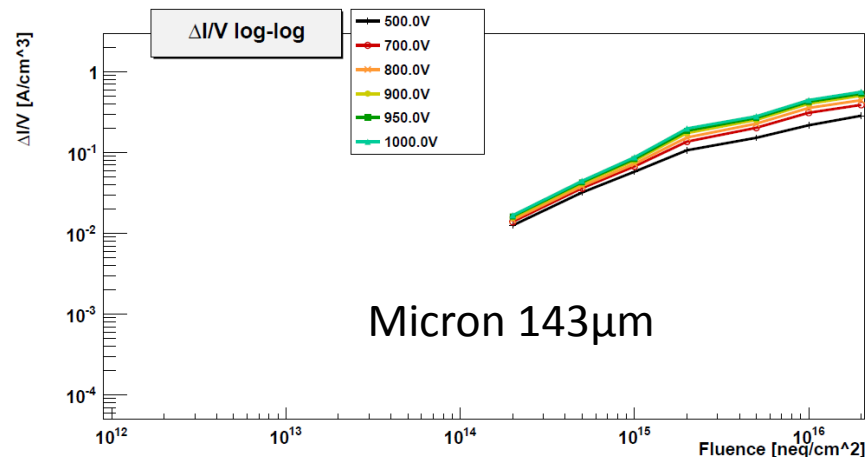
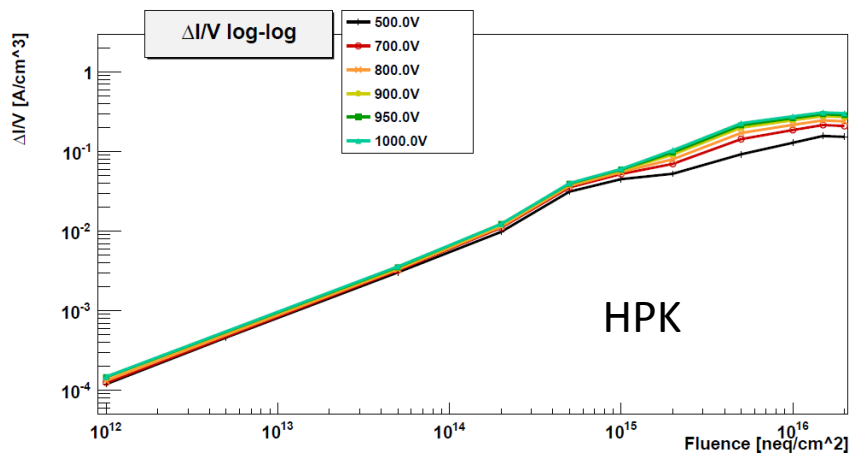


Alpha values divided by theoretical value

Annealing time [min]	α [10^{-17}A/cm] at 21°C
0.3d (=470 min)	6.40 ± 0.43
10d (=14400min)	4.32 ± 0.29
30d (=43220min)	3.50 ± 0.23



$\Delta I/V$ vs ϕ (0.3d)



- $\Delta I/V$ as function of fluence
- 0.3d annealing
- New measurements included



- Room temperature annealing of irradiated RD50 charge multiplication sensors
 - $1 \times 10^{15} n_{eq}/cm^2$: expected annealing profile
 - $5 \times 10^{15} n_{eq}/cm^2$: increasing collected charge with increasing annealing time -> charge multiplication
- Long-term bias voltage test
 - No clear systematics observed from the presented measurements
 - See talk of C. Betancourt (this workshop, Thursday) for more details
- IV study:
 - Difference of the activation energy E_g for low fluence ($\leq 2 \times 10^{15} n_{eq}/cm^2$) and high fluence ($\geq 5 \times 10^{15} n_{eq}/cm^2$) sensors
 - Low fluence $\approx (1.17 \pm 0.03) eV$
 - High fluence $\approx (1.05 \pm 0.08) eV$
 - Also different current related damage rate α
 - High fluence significantly lower
 - With increasing annealing time the difference between the high fluence α and the theoretical value decrease



Backup



- IV scaling:

$$\frac{I(T_2)}{I(T_1)} = \left(\frac{T_2}{T_1}\right)^2 \exp\left(\frac{-E_g}{2k_B} \frac{T_1 - T_2}{T_1 T_2}\right)$$

E_g : activation energy (1.214±0.014eV [1]); T_1 : measurement temperature, T_2 : scaling temperature; k_B : Boltzmann constant

Use for scaling of current to different temperatures, determination of E_g from measurement

- Investigate behaviour of current for irradiated sensors

$$\frac{I(\Phi_{eq}) - I(\Phi_0)}{V} = \alpha \Phi_{eq} \quad \text{Only valid up to } \sim 1 \times 10^{15} \text{ n}_{eq}/\text{cm}^2$$

V : depleted volume; Φ_{eq} : equivalent fluence; $I(\Phi_0)$: nonirradiated current ; α : current related damage rate

Determination of α from measurements

[1]: A. Chilingarov; *Temperature dependence of the current generated in Si bulk*; 2013_JINST_8_P10003